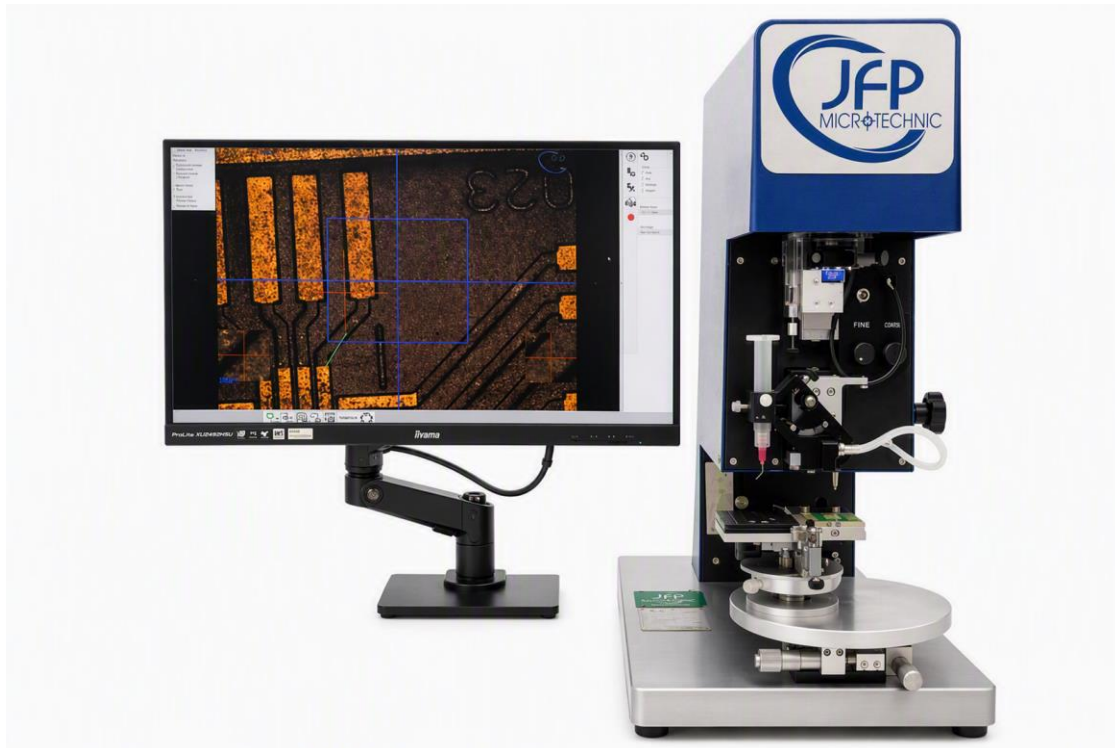


MPS

MANUAL PLACER SYSTEM

The MPS is a compact and highly accurate manual pick & place system designed for die attach, SMD assembly, epoxy dispensing and laboratory process development. Its true vertical motion and vision-assisted placement enable precise positioning of delicate components and small substrates.



PICK AND PLACE
EPOXY DIE BONDER

MICROMETRIC X-Y STAGE

VACUUM PICK-UP

HIGH PRECISION
ALIGNMENT

Flexible by design

The MPS combines precision mechanics, advanced vision assistance and ergonomic operation in a compact benchtop system. Suitable for research laboratories, prototype assembly and low-volume production.

Explore the possibilities

Contact Micronnect for configuration advice, a demonstration, training and service.

KEY BENEFITS

- High-accuracy die placement
- True vertical Z-axis movement
- Vision-assisted alignment system
- Pick & place and dispensing capability
- Heated workholder options
- Compact laboratory footprint

Technology and configuration

Compact, precise and easy to operate, the MPT delivers reliable bond strength testing for laboratory and production environments.

01 True Vertical Motion

Accurate vertical movement ensures precise component placement without lateral displacement.

02 Rocking Head System

Integrated rocking head supports pick & place, dispensing and stamping applications.

03 Precision X-Y-Theta Adjustment

Micrometric stage allows precise substrate positioning and rotation alignment.

04 Vision Alignment Technology

Camera overlays and digital crosshairs support accurate die and substrate alignment

TECHNICAL DATA

Substrate Size	Up to 350 mm
X-Y Travel	25 x 25 mm
Work Platform	200 x 200 mm
Work Height	100 mm
Troat Depth	200 µm
Low Placement Force	< 5 g
Dimensions	270 × 500 × 352 mm
Weight	17 kg

Specifications are based on the supplied product information. Final execution may vary by configuration.

OPTIONS

-  Precision X-Y-Theta Stage
-  Multi-Wafer Platform
-  Heated Workholder
-  HD Inspection Camera
-  Vacuum Pick-up Tools
-  Hot Gas (SMD REFLOW)

High-precision X-Y positioning combined with smooth rotational adjustment allows accurate alignment of dies, substrates and components before placement.

Find the right configuration for your process

Contact us for technical advice or a demonstration.

CONTACT